AFBR-710USMZ

10GbE, 850-nm, SFP+ USR, 100m on OM3 MMF Transceiver

Description

The Broadcom® AFBR-710USMZ transceiver is part of a family of SFP+ products. This transceiver uses the Broadcom 850-nm Vertical Cavity Surface Emitting Laser (VCSEL) and PIN detector technology to provide a transceiver to support 100m reach on OM3 MMF versus the 300m 10GBASE-SR standard. The AFBR-710USMZ transceiver is designed to enable 10 Gigabit Ethernet (GbE) equipment designs with very high port density based on the new electrical and mechanical specification enhancements to the well-known SFP specifications developed by the SFF Committee. These specifications are referred to as SFP+ to recognize these enhancements to previous SFP specifications used for lower speed products. Broadcom is an active participant in the SFF Committee specification development activities.

Related Products

- AFBR-709SMZ, 10GbE, 850-nm, 10GBASE-SR, SFP+ transceiver, 300m reach on OM3 MMF
- AFBR-739DMZ SFP+ 10Gb/1Gb GbE 10GBASE-SR transceiver for operation in 300m reach using OM3 MMF.
- AFCT-739SMZ SFP+ 10GbE 10GBASE- LR transceiver for operation in SMF link applications to 10 km
- AFCT-5716Z SFP+ evaluation board, which provides the designer with a convenient means for evaluating SFP+ fiber-optic transceivers.

Features

- Broadcom 850-nm VCSEL source and transmitter optical subassembly technology
- Broadcom PIN detector and receiver optical subassembly technology
- Typical power dissipation 600 mW
- Full digital diagnostic management interface
- Broadcom SFP+ package design enables equipment EMI performance in high port density applications with margin to Class B limits

Specifications

- Optical interface specifications provide 100m reach on OM3 MMF when interoperating with other 10GBASE-SR or SFP+USR interfaces at the remote end of the link
- Electrical interface specifications per SFF Committee SFF 8431 Specifications for Enhanced 8.5 and 10 Gigabit Small Form Factor Pluggable Module (SFP+)
- Management interface specifications per SFF Committee SFF 8431 and SFF 8472 Diagnostic Monitoring Interface for Optical Transceivers with some adjustment
- Mechanical specifications per SFF Committee SFF 8432 Improved Pluggable Formfactor (IPF)
- LC duplex optical connector interface confirming to ANSI TIA/EA 604-10 (FOCIS 10A)
- Compliant to Restriction on Hazardous Substances (RoHS) per EU and China requirements
- Class 1 eye safety per requirements of IEC 60825-1/ CDRH

Installation

The AFBR-710USMZ transceiver package is compliant with the SFF 8432 Improved Pluggable Formfactor (IPF) housing specification for the SFP+. It can be installed in any INF-8074 or SFF-8431/2 compliant Small Form Pluggable (SFP) port regardless of host equipment operating status. The AFBR-708SMZ is hot-pluggable, allowing the module to be installed while the host system is operating and online. Upon insertion, the transceiver housing makes initial contact with the host board SFP cage, mitigating potential damage due to electrostatic discharge (ESD).

Digital Diagnostic Interface and Serial Identification

The two-wire interface protocol and signaling detail are based on SFF-8431. Conventional EEPROM memory, bytes 0–255 at memory address 0xA0, is organized in compliance with SFF-8431. New digital diagnostic information, bytes 0–255 at memory address 0xA2, is compliant to SFF-8472. The new diagnostic information provides the opportunity for predictive failure identification, compliance prediction, fault isolation, and component monitoring.

Predictive Failure Identification

The AFBR-710USMZ predictive failure feature allows a host to identify potential link problems before system performance is impacted. Prior identification of link problems enables a host to service an application using "failover" to a redundant link or replace a suspect device, maintaining system uptime in the process. For applications where ultra-high system uptime is required, a digital SFP provides a means to monitor two real-time laser metrics associated with observing laser degradation and predicting failure: average laser bias current (Tx_Bias) and average laser optical power (Tx_Power).

Compliance Prediction

Compliance prediction is the ability to determine if an optical transceiver is operating within its operating and environmental requirements. AFBR-710USMZ devices provide real-time access to transceiver internal supply voltage and temperature, allowing a host to identify potential component compliance issues. Received optical power is also available to assess compliance of a cable plant and remote transmitter. When operating out of requirements, the link cannot guarantee error-free transmission.

Fault Isolation

The fault isolation feature allows a host to quickly pinpoint the location of a link failure, minimizing downtime. For optical links, the ability to identify a fault at a local device, remote device, or cable plant is crucial to speeding service of an installation. AFBR-710USMZ real-time monitors of Tx_Bias, Tx_Power, Vcc, Temperature, and Rx_Power can assess local transceiver current operating conditions. In addition, status flags TX_DISABLE and Rx Loss of Signal (LOS) are mirrored in memory and available using the two-wire serial interface.

Component Monitoring

Component evaluation is a more casual use of the AFBR-710USMZ real-time monitors of Tx_Bias, Tx_Power, Vcc, Temperature, and Rx_Power. Potential uses are as debugging aids for system installation and design and transceiver parametric evaluation for factory or field qualification. For example, temperature per module can be observed in high-density applications to facilitate thermal evaluation of blades, PCI cards, and systems.

Figure 1: Transceiver Functional Diagram
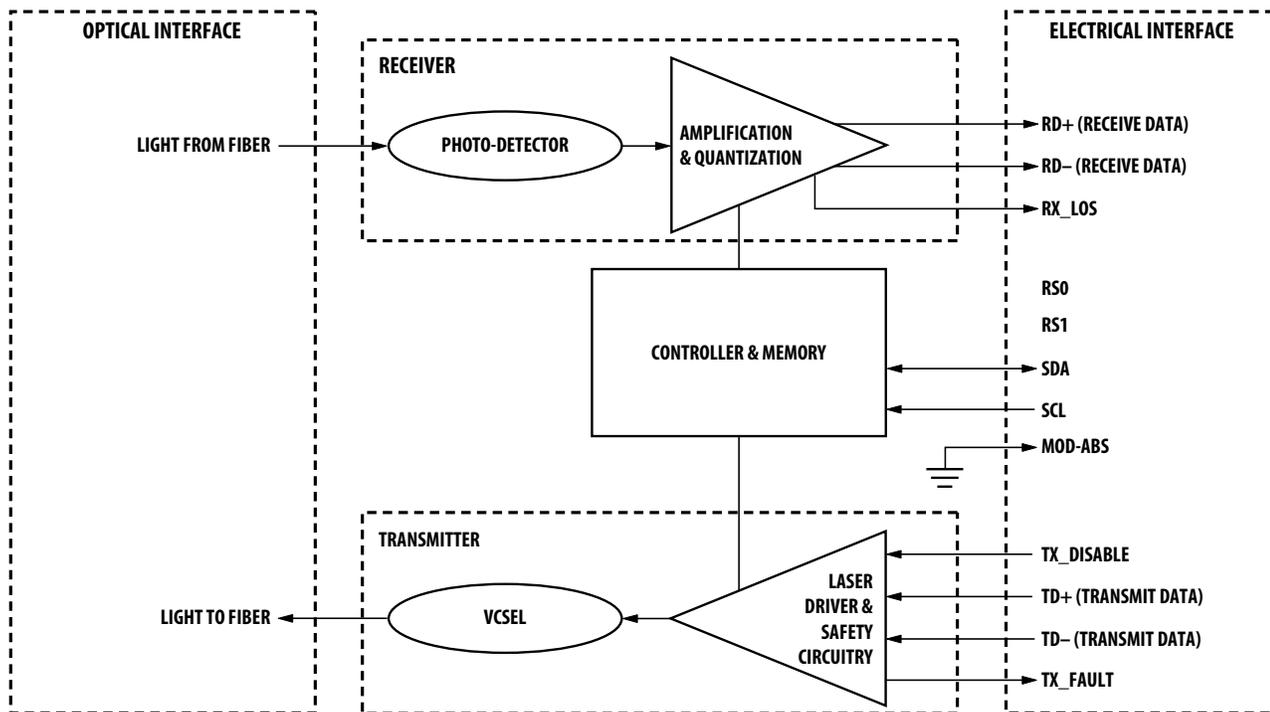
Transmitter Section

The transmitter section includes the Transmitter Optical Sub-Assembly (TOSA) and laser driver circuitry. The TOSA, containing a Broadcom designed and manufactured 850-nm VCSEL light source, is located at the optical interface and mates with the LC optical connector. The TOSA is driven by an IC that uses the incoming differential high-speed logic signal to modulate the laser diode driver current. This Tx laser driver circuit regulates the optical power at a constant level provided the incoming data pattern is DC balanced.

Transmit Disable (TX_DISABLE)

The AFBR-710USMZ accepts an LVTTL-compatible transmit disable control signal input that shuts down the transmitter optical output. A high signal implements this function, while a low signal allows normal transceiver operation. In the event of a fault (for example, eye safety circuit activated), cycling this control signal resets the

module as depicted in Figure 7. An internal pull-up resistor disables the transceiver transmitter until the host pulls the input low. TX_DISABLE can also be asserted using the two-wire interface (address A2h, byte 110, bit 6) and monitored (address A2h, byte 110, bit 7).

The contents of A2h, byte 110, bit 6 are logic ORed with hardware TX_DISABLE (contact 3) to control transmitter operation.

Transmit Fault (TX_FAULT)

A catastrophic laser fault activates the transmitter signal, TX_FAULT, and disables the laser. This signal is an open collector output (pull-up required on the host board). A low signal indicates normal laser operation, and a high signal indicates a fault. The TX_FAULT is latched high when a laser fault occurs and is cleared by toggling the TX_DISABLE input or power-cycling the transceiver. The transmitter fault condition can also be monitored using the two-wire serial interface (address A2, byte 110, bit 2).

Receiver Section

The receiver section includes the Receiver Optical Sub-Assembly (ROSA) and the amplification/quantization circuitry. The ROSA, containing a PIN photodiode and custom transimpedance amplifier, is located at the optical interface and mates with the LC optical connector. The ROSA output is fed to a custom IC that provides post-amplification and quantization.

Receiver Loss of Signal (Rx_LOS)

The post-amp IC also includes transition-detection circuitry that monitors the AC level of incoming optical signals and provides an LVTTL/CMOS compatible status signal to the host. A high status signal indicates loss of modulated signal, indicating link failures, such as broken fiber or a failed transmitter. Rx_LOS can also be monitored using the two-wire serial interface (address A2h, byte 110, bit 1).

Functional Data I/O

The AFBR-710USMZ interfaces with the host circuit board through the 20-contact SFP+ electrical connector. See Table 2 for contact descriptions. The module edge connector is shown in Figure 4. The host board layout for this interface is depicted in Figure 8.

The AFBR-708SMZ high-speed transmit and receive interfaces require SFF-8431-compliant signal lines on the host board. To simplify board requirements, biasing resistors and AC-coupling capacitors are incorporated into the SFP+ transceiver module (per SFF-8431) and, hence, are not required on the host board. The TX_DISABLE, TX_ FAULT, and RX_LOS signals require LVTTL signals on the host board (per SFF-8431) if used. If an application does not take advantage of these functions, take care to ground TX_DISABLE to enable normal operation.

Figure 2 depicts the recommended interface circuit to link the AFBR-710USMZ to supporting physical layer ICs. Timing for the dedicated SFP+ control signals implemented in the transceiver are listed in Figure 7.

Application Support

An evaluation kit and reference designs are available to assist in evaluation of the AFBR-710USMZ. Contact your local Field Sales representative for availability and ordering details.

CAUTION! There are no user serviceable parts nor maintenance requirements for the AFBR-710USMZ. All mechanical adjustments are made at the factory prior to shipment. Tampering with, modifying, misusing, or improperly handling the AFBR-710USMZ will void the product warranty. It may also result in improper operation and possibly overstress the laser source. Performance degradation or device failure may result. Connection of the AFBR-710USMZ to a light source not compliant with IEEE Std. 802.3ae Clause 52 and the SFF-8341 specifications, operating above maximum operating conditions or in a manner inconsistent with its design and function may result in exposure to hazardous light radiation and may constitute an act of modifying or manufacturing a laser product. Persons performing such an act are required by law to recertify and re-identify the laser product under the provisions of U.S. 21 CFR (Subchapter J) and TUV.

Customer Manufacturing Processes

This module is pluggable and is not designed for aqueous wash, IR reflow, or wave soldering processes.

Ordering Information

Contact your local Field Sales engineer or one of Broadcom's franchised distributors for ordering information. For technical information, visit the Broadcom website at www.broadcom.com. For information related to SFF Committee documentation, visit www.sffcommittee.org.

Regulatory Compliance

The AFBR-710USMZ complies with all applicable laws and regulations as detailed in Table 1. Certification level is dependent on the overall configuration of the host equipment. The transceiver performance is offered as a figure of merit to assist the designer.

Electrostatic Discharge (ESD)

The AFBR-710USMZ is compatible with ESD levels found in typical manufacturing and operating environments as described in Table 1. In the normal handling and operation of optical transceivers, ESD is of concern in two circumstances.

The first case is during handling of the transceiver prior to insertion into an SFP compliant cage. To protect the device, use normal ESD handling precautions. These include use of grounded wrist straps, workbenches, and floor wherever a transceiver is handled.

The second case to consider is static discharges to the exterior of the host equipment chassis after installation. If the optical interface is exposed to the exterior of host equipment cabinet, the transceiver may be subject to system-level ESD requirements.

Electromagnetic Interference (EMI)

Equipment incorporating 10-Gb transceivers is typically subject to regulation by the FCC in the United States, CENELEC EN55022 (CISPR 22) in Europe, and VCCI in Japan. The AFBR-708SMZ enables equipment compliance to these standards detailed in Table 1. The metal housing and shielded design of the AFBR-710USMZ minimizes the EMI challenge facing the equipment designer. For superior EMI performance, equipment designs should use SFP+ cages per SFF 8432.

RF Immunity (Susceptibility)

Due to its shielded design, the EMI immunity of the AFBR-710USMZ exceeds typical industry standards.

Eye Safety

The AFBR-710USMZ provides Class 1 (single fault tolerant) eye safety by design and has been tested for compliance with the requirements listed in Table 1. The eye safety circuit continuously monitors the optical output power level and disables the transmitter upon detecting a condition beyond the scope of Class 1 certification Such conditions can be due to inputs from the host board (Vcc fluctuation, unbalanced code) or a fault within the transceiver. US CDRH and EU TUV certificates are listed in Table 1.

Flammability

The AFBR-710USMZ optical transceiver is made of metal and high strength, heat resistant, chemical resistant, and UL 94V-0 flame-retardant plastic.

Table 1: Regulatory Compliance

| Feature	Test Method	Performance
Electrostatic Discharge (ESD) to the Electrical Pins	JEDEC A114	Class 1 (> 2000V) > 1000V for high speed signal pins TD+-, RD+-
Electrostatic Discharge (ESD) to the Duplex LC Receptacle	IEC 61000-4-2	Typically, no damage occurs with 25 kV when the duplex LC connector receptacle is contacted by a Human Body Model probe.
	IEC 61000-4-2	10 contacts of 8 kV on the electrical faceplate with the device inserted into a panel.
Electrostatic Discharge (ESD) to the Optical Connector	IEC 61000-4-2	Air discharge of 15 kV (min.), contact to connector without damage.
Electromagnetic Interference (EMI)	FCC Class B CENELEC EN55022 Class B (CISPR 22A) VCCI Class A	System margins are dependent on the customer board and chassis design.
Immunity	IEC 61000-4-3	Typically shows no measurable effect from a 10-V/m field swept from 10 MHz to 1 GHz.
Laser Eye Safety and Equipment Type Testing	Complies with 21 CFR 1040.10 except for conformance with IEC 60825-1 Ed. 3., as described in Laser Notice No. 56, dated May 8, 2019. IEC/EN 62368-1 IEC/EN 60825-1 IEC/EN 60825-2	CDRH certification # 9720151-197 TUV file # R 50394970
Component Recognition	Underwriters Laboratories and Canadian Standards Association Joint Component Recognition for Information Technology Equipment including Electrical Business Equipment	UL File # 484615
RoHS Compliance		Less than 100 ppm of cadmium and less than 1000 ppm of lead, mercury, hexavalent chromium, polybrominated biphenyls (PPBs) polybrominated biphenyl ethers (PBDEs), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate

Figure 2: Typical Application Configuration
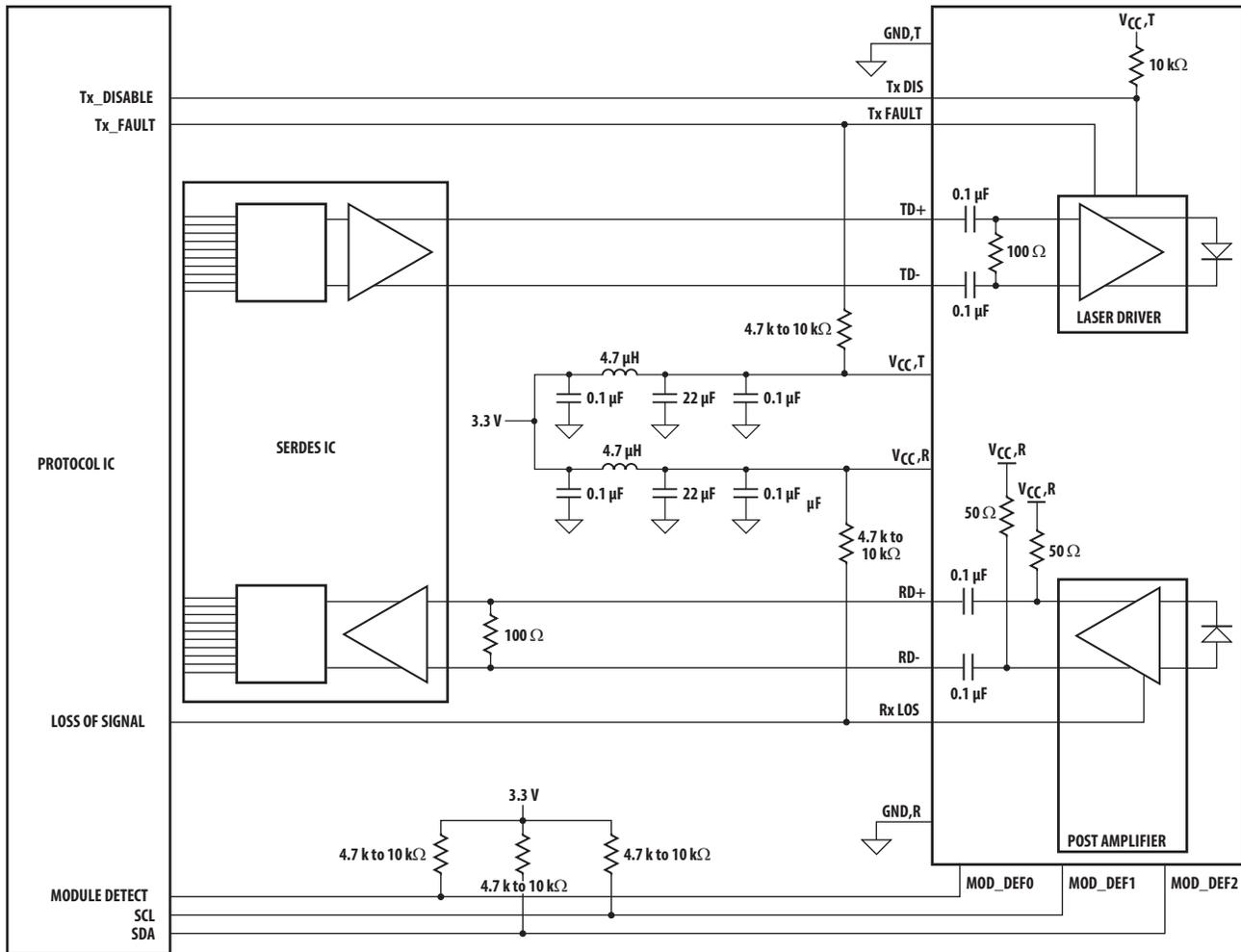
**Figure 3: Recommended Power Supply Filter**
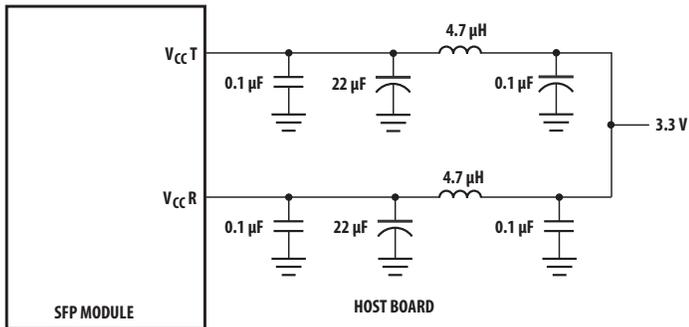
NOTE: INDUCTORS MUST HAVE LESS THAN 1Ω SERIES RESISTANCE TO LIMIT VOLTAGE DROP TO THE SFP MODULE.

Table 2: Contact Description

Contact	Symbol	Function/Description	Notes
1	$V_{ee}T$	Transmitter Signal Ground	a
2	TX_FAULT	Transmitter Fault (LVTTL-O) – High indicates a fault condition	b
3	TX_DISABLE	Transmitter Disable (LVTTL-I) – High or open disables the transmitter	c
4	SDA	Two Wire Serial Interface Data Line (LVCMOS – I/O) (same as MOD-DEF2 in INF-8074)	d
5	SCL	Two Wire Serial Interface Clock Line (LVCMOS – I/O) (same as MOD-DEF1 in INF-8074)	d
6	MOD_ABS	Module Absent (Output), connected to VeeT or VeeR in the module	e
7	RS0	Rate Select 0 – Not used, Presents high input impedance.	
8	RX_LOS	Receiver Loss of Signal (LVTTL-O)	b
9	RS1	Rate Select 1 – Not used, Presents high input impedance.	
10	$V_{ee}R$	Receiver Signal Ground	a
11	$V_{ee}R$	Receiver Signal Ground	a
12	RD–	Receiver Data Out Inverted (CML-O)	
13	RD+	Receiver Data Out (CML-O)	
14	$V_{ee}R$	Receiver Signal Ground	
15	$V_{cc}R$	Receiver Power + 3.3V	
16	$V_{cc}T$	Transmitter Power + 3.3V	
17	$V_{ee}T$	Transmitter Signal Ground	a
18	TD+	Transmitter Data In (CML-I)	
19	TD–	Transmitter Data In Inverted (CML-I)	
20	$V_{ee}T$	Transmitter Signal Ground	a

a. The module signal grounds are isolated from the module case.

b. This is an open collector/drain output that on the host board requires a 4.7-kΩ to 10-kΩ pull-up resistor to V_{cc}Host. See Figure 2.

c. This input is internally biased high with a 4.7-kΩ to 10-kΩ pull-up resistor to $V_{cc}T$.

d. Two-wire serial interface clock and data lines require an external pull-up resistor dependent on the capacitance load.

e. This is a ground return that on the host board requires a 4.7-kΩ to 10-kΩ pull-up resistor to V_{cc}Host.

Figure 4: Module Edge Connector Contacts
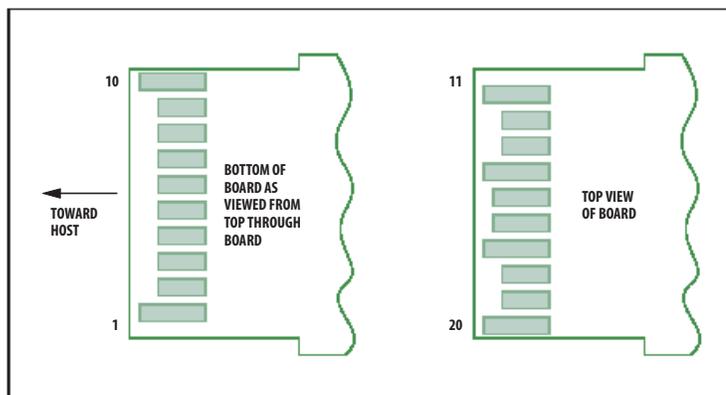
Stress in excess of any of the individual Absolute Maximum Ratings can cause immediate catastrophic damage to the module even if all other parameters are within Recommended Operating Conditions. It should not be assumed that limiting values of more than one parameter can be applied concurrently. Exposure to any of the Absolute Maximum Ratings for extended periods can adversely affect reliability.

Table 3: Absolute Maximum Ratings

Parameter	Symbol	Min.	Max.	Units	Notes
Storage Temperature	T_S	–40	85	°C	
Case Operating Temperature	T_C	–40	85	°C	
Relative Humidity (Non-condensing)	RH	5	95	%	
Supply Voltage	$V_{cc}T$, $V_{cc}R$	–0.3	3.8	V	a
Low Speed Input Voltage		–0.5	Vcc + 0.5	V	
Two-Wire Interface Input Voltage		–0.5	Vcc + 0.5	V	
High Speed Input Voltage, Single-Ended		–0.3	Vcc + 0.5	V	
High Speed Input Voltage, Differential		—	2.5	V	
Low Speed Output Current		–20	20	mA	
Optical Receiver Input Average Power		—	0	dBm	

a. The module supply voltages, $V_{cc}T$ and $V_{cc}R$, must not differ by more than 0.5V or damage to the device may occur.

Recommended Operating Conditions specify parameters for which the electrical and optical characteristics hold unless otherwise noted. Optical and electrical characteristics are not defined for operation outside the Recommended Operating Conditions, reliability is not implied and damage to the module may occur for such operation over an extended period of time.

Table 4: Recommended Operating Conditions

Parameter	Symbol	Min.	Max.	Units	Figures	Notes
Case Operating Temperature	T_C	0	70	°C		a
Module Supply Voltage	$V_{cc}T$, $V_{cc}R$	3.135	3.465	V	3	
Host Supply Voltage	$V_{cc}Host$	3.14	3.46	V		
Signal Rate		10.311	10.313	Gbaud		
Power Supply Noise Tolerance		—	66 10 Hz to 10 MHz	mVp-p	3	
Tx Input Single-Ended DC Voltage Tolerance (Ref. VeeT)	V	–0.3	4.0	V		
Rx Output Single-Ended Voltage Tolerance	V	–0.3	4.0	V		

a. Ambient operating temperature limits are based on the case operating temperature limits and are subject to the host system thermal design. See Figure 8 for the module T_C reference point.

The following characteristics are defined over the Recommended Operating Conditions unless otherwise noted. Typical values are for T_C = 40°C. $V_{cc}T$ and $V_{cc}R$ = 3.3V.

Table 5: Low-Speed Signal Electrical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Units	Notes
Module Supply Current	I_{CC}	—	180	289	mA	a
Power Dissipation	P_{DISS}	—	600	1000	mW	
TX_FAULT, RX_LOS	I_{OH}	–50	—	+37.5	µA	b
	V_{OL}	–0.3	—	0.4	V	
TX_DISABLE	V_{IH}	2.0	—	$V_{cc}T + 0.3$	V	c
	V_{IL}	–0.3	—	0.8	V	

a. Supply current includes both $V_{cc}T$ and $V_{cc}R$ connections.

b. Measured with a 4.7-kΩ load to V_{cc}Host.

c. TX_DISABLE has an internal 4.7-kΩ to 10-kΩ pull-up to $V_{cc}T$.

The following characteristics are defined over the Recommended Operating Conditions unless otherwise noted. Typical values are for T_C = 40°C. $V_{cc}T$ and $V_{cc}R$ = 3.3V.

Table 6: High-Speed Signal Electrical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unitw	Notes
Tx Input Differential Voltage (TD +/–)	V_I	180	—	700	mV	a
Tx Input AC Common Mode Voltage Tolerance		—	—	15	mV(RMS)	
Tx Input Differential S-parameter (100Ω Ref.)	SDD11	—	—	Note b Note c	dB dB	0.01 to 4.1 GHz 4.1 to 11.1GHz
Tx Input Differential to Common Mode Conversion (25Ω Ref.)	SCD11	—	—	–10	dB	0.01 to 11.1 GHz
Rx Output Differential Voltage (RD +/–)	Vo	300	—	850	mV	d
Rx Output Termination Mismatch at 1 MHz	ΔZ_m	—	—	5	%	
Rx Output AC Common Mode Voltage		—	—	7.5	mV(RMS)	e
Rx Output Rise and Fall Time (20% to 80%)	tr, tf	28	—	—	ps	
Rx Output Total Jitter	TJ	—	—	0.70	Ulp-p	
Rx Output Deterministic Jitter	DJ	—	—	0.42	Ulp-p	
Rx Output Differential S-parameter (100Ω Ref.)	SDD22	—	—	Note f Note g	dB dB	0.01 to 4.1 GHz 4.1 to 11.1GHz
Rx Output Common Mode Reflection Coefficient (25Ω Ref.)	SCC22	—	—	Note h Note i	dB dB	0.01 to 2.5 GHz 2.5 to 11.1 GHz
Receiver Output Eye Mask		—	—	—		See Figure 5

a. Internally AC coupled and terminated (100Ω differential).

b. Maximum reflection coefficient given by equation SDD11(dB) = –12 + 2 × SQRT(f), with f in GHz.

c. Maximum reflection coefficient given by equation SDD11(dB) = –6.3 + 13Log10(f / 5.5), with f in GHz.

d. Internally AC coupled but requires an external load termination (100Ω differential).

e. The RMS value is measured by calculating the standard deviation of the histogram for one UI of the common mode signal.

f. Maximum reflection coefficient given by equation SDD22(dB) = –12 + 2 × SQRT(f), with f in GHz.

g. Maximum reflection coefficient given by equation SDD22(dB) = –6.3+13Log10(f / 5.5), with f in GHz.

h. Reflection coefficient given by equation SCC22(dB) < –12 + 2.8 × f, with f in GHz.

i. Reflection coefficient given by equation SCC22(dB) < –5.2 + 0.08 × f, with f in GHz.

**Figure 5: Receiver Electrical Optical Eye Mask Definition**
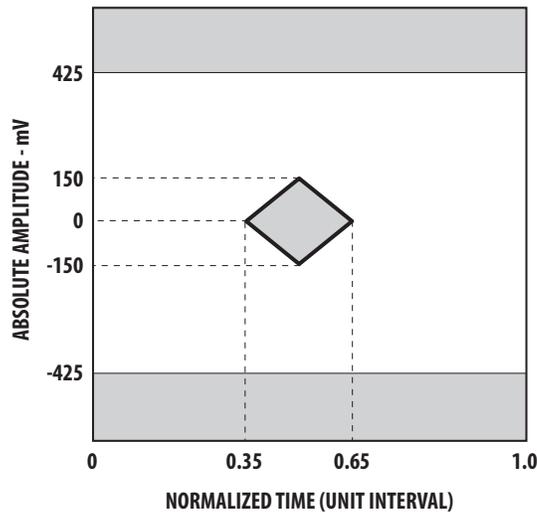
**Figure 6: Transmitter Optical Eye Mask Definition**

.
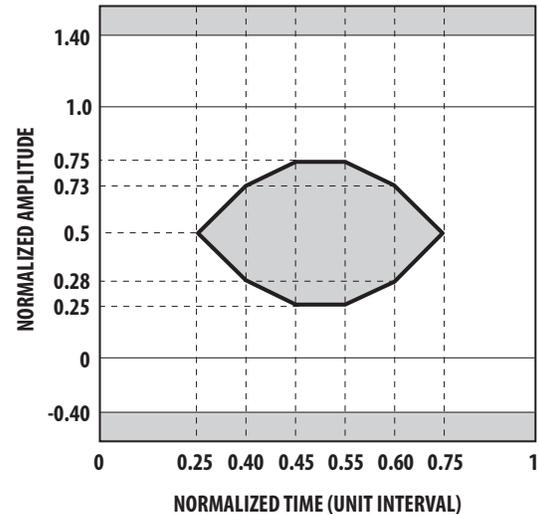
Table 7: Two-Wire Interface Electrical Characteristics

Parameter	Symbol	Min.	Max.	Units	Conditions
Host Vcc Range	$V_{cc}HTWI$	3.135	3.465	V	
SCL and SDA	V_{OL}	0.0	0.40	V	
	V_{OH}	$V_{cc}HTWI - 0.5$	$V_{cc}HTWI + 0.3$	V	Rp[a] pulled to $V_{cc}HTWI$, measured at host side of connector
SCL and SDA	V_{IL}	–0.3	$V_{cc}T \times 0.3$	V	
	V_{IH}	$V_{cc}T \times 0.7$	$V_{cc}T + 0.5$	V	
Input Current on the SCL and SDA Contacts	I_I	–10	10	µA	
Capacitance on SCL and SDA Contacts	C_i[b]	—	14	pF	
Total Bus Capacitance for SCL and for SDA	C_b[c]	—	100	pF	At 400 kHz, 3.0 kΩ Rp, max.
					At 100 kHz, 8.0 kΩ Rp, max.
		—	290	pF	At 400 kHz, 1.1 kΩ Rp, max.
					At 100 kHz, 2.75 kΩ Rp, max.

a. Rp is the pull-up resistor. Active bus termination may be used by the host in place of a pull-up resistor. Pull ups can be connected to various power supplies; however, the host board design ensures that no module contact has voltage exceeding $V_{cc}T$ or $V_{cc}R$ by 0.5V nor requires the module to sink more than 3.0-mA current.

b. C_i is the capacitance looking into the module SCL and SDA contacts.

c. C_b is the total bus capacitance on the SCL or SDA bus.

The following characteristics are defined over the Recommended Operating Conditions unless otherwise noted. Typical values are for T_C = 40°C. $V_{cc}T$ and $V_{cc}R$ = 3.3V.

Table 8: Optical Specifications

Parameter	Min.	Typ.	Max.	Units	Notes
Link Specifications					
Fiber Core	—	50	—	µm	
Fiber BW	2000	—	—	MHz km	
Signal Rate		10312.5 ± 100 ppm	—	Mbaud	
BER	—	—	10^{-12}		
Worst Case Range	2	—	100	m	a
Allocated Connector Loss	—	—	1.50	dB	
Transmitter Optical Specifications					
Center Wavelength	840	—	860	nm	
RMS Spectral Width	—	—	0.65	nm	
Average Launch Power	–7.3	—	–1.3	dBm	b
OMA Launch Power	–5	—	—	dBm	
Optical Rise/Fall Time (20% to 80%)	—	35	—	ps	Informative
Transmitter and Dispersion Penalty	—	—	3.5	dB	c
RIN_{12} OMA	—	—	–128	dB/Hz	
Average Launch Power, Off	—	—	–30.0	dBm	
Extinction Ratio	3.0	—	—	dB	
Transmitter Output Eye Mask	—	—	—		See Figure 6
Transmitter Launched Encircled Flux	—	—	—		d
Optical Return Loss Tolerance	—	—	12	dB	
Receiver Optical Specifications					
Center Wavelength	840	—	860	nm	
Received Power to Receive Power (Pave) Overload	–1.0	—	—	dBm	
Receiver Sensitivity – Average	—	—	–9.9	dBm	Informative
Receiver Sensitivity – OMA	—	—	–11.1	dBm	Informative
Stressed Receiver Sensitivity, OMA	—	—	–7.5	dBm	e
Receiver Reflectance	—	—	–12	dBm	
RX_LOS (OMA) Off	—	—	–12	dBm	
RX_LOS (OMA) On	–30	—	—	dBm	
RX_LOS (OMA) Hysteresis	0.5	—	—	dB	

a. The reach achievable on OM3 MMF when interoperating with either 10G BASE-SR or 10G BASE-USR interfaces at the remote end of the link. The typical reach on OM2 MMF is 30m and 10m on OM1 MMF.

b. The maximum average launch power is the lesser of the Class 1 eye safety limit or the average receive power maximum at the receive side of –1.0 dBm.

c. TDP measured with 100m OM3 fiber or per IEEE 802.3 Clause 52 except with 21-ps transversal filter instead of 55-ps transversal filter.

d. The transmitter's launch condition meets the requirements of OM3 multimode fiber as detailed in TIA-492-AAA-C.

e. The stressed receiver sensitivity is evaluated with an input optical test signal adjusted for the 100m OM3 link distance. The stress parameters are VECP = 1.6-dBm minimum and Jitter = 0.3-UI minimum.

The following characteristics are defined over the Recommended Operating Conditions unless otherwise noted.

Table 9: Control Functions: Low-Speed Signals Timing Characteristics

Parameter	Symbol	Min.	Max.	Units	Notes	Figures
TX_DISABLE Assert Time	t_off	—	10	µs	a	7
TX_DISABLE Negate Time	t_on	—	2	ms	b	7
Time to initialize, including reset of TX_FAULT	t_init	—	300	ms	c	7
TX_FAULT Assert Time	t_fault	—	1	ms	d	7
TX_DISABLE to Reset	t_reset	10	—	µs	e	7
RX_LOS Assert Time	t_los_on	—	100	µs	f	7
RX_LOS Deassert Time	t_los_off	—	100	µs	g	7

a. Time from rising edge of TX_DISABLE to when the optical output falls below 10% of nominal. A 10-ms interval between assertions of TX_ DISABLE is required.

b. Time from falling edge of TX_DISABLE to when the modulated optical output rises above 90% of nominal.

c. Time from power on or falling edge of TX_DISABLE to when the modulated optical output rises above 90% of nominal and the two-wire interface is available.

d. From power on or negation of TX_FAULT using TX_DISABLE.

e. Time TX_DISABLE must be held high to reset the laser fault shutdown circuitry.

f. Time from loss of optical signal to Rx_LOS Assertion.

g. Time from valid optical signal to Rx_LOS Deassertion.

The following characteristics are defined over the Recommended Operating Conditions unless otherwise noted.

**Table 10: Control Functions: Two-Wire Interface Timing Characteristics**

Parameter	Symbol	Min.	Max.	Units	Notes
TX_DISABLE Assert Time	t_off_twi	—	100	ms	a
TX_DISABLE Negate Time	t_on_twi	—	100	ms	b
TX_FAULT Assert Time	t_fault_twi	—	100	ms	c
Rx_LOS Assert Time	t_loss_on_twi	—	100	ms	d
Rx_LOS Deassert Time	t_loss_off_twi	—	100	ms	e
Analog Parameter Data Ready	t_data	—	1000	ms	f
Two-Wire Interface Ready	t_serial	—	300	ms	g
Write Cycle Time Parameter	t_write	—	80	ms	h
Two-Wire Interface Clock Rate	f_serial_clock	—	400	kHz	i
Time Bus Free before New Transmission Can Start	t_BUF	20	—	s	j

a. Time from two-wire interface assertion of TX_DISABLE (A2h, byte 110, bit 6) to when the optical output falls below 10% of nominal. Measured from falling clock edge after stop bit of write transaction.

b. Time from two-wire interface deassertion of TX_DISABLE (A2h, byte 110, bit 6) to when the modulated optical output rises above 90% of nominal.

c. Time from fault to two-wire interface TX_FAULT (A2h, byte 110, bit 2) asserted.

d. Time for two-wire interface assertion of Rx_LOS (A2h, byte 110, bit 1) from loss of optical signal.

e. Time for two-wire interface deassertion of Rx_LOS (A2h, byte 110, bit 1) from presence of valid optical signal.

f. From power-on to data ready bit asserted (A2h, byte 110, bit 0). Data ready indicates analog monitoring circuitry is functional.

g. Time from power-on until module is ready for data transmission over the two-wire interface (reads or writes over A0h and A2h).

h. Time from the stop bit to completion of a 1-byte to 8-byte write command. For a 1-byte to 4-byte write, the maximum cycle time is 40 ms and for a 5-byte to 8-byte write, the maximum cycle time is 80 ms.

i. The module may clock stretch for f_serial_clock greater than 100 kHz.

j. Between STOP and START. Refer to SFF 8431 Section 4.3.

The following characteristics are defined over the Recommended Operating Conditions unless otherwise noted. Typical values are for T_C = 40°C. $V_{cc}T$ and $V_{cc}R$ = 3.3V.

Table 11: Transceiver Digital Diagnostic Monitor (Real Time Sense) Characteristics

Parameter	Symbol	Min.	Units	Notes
Transceiver Internal Temperature Accuracy	T_{INT}	±3.0	°C	Temperature is measured internal to the transceiver. Valid from –10°C to 85°C case temperature.
Transceiver Internal Supply Voltage Accuracy	V_{INT}	±0.1	V	Supply voltage is measured internal to the transceiver and can, with less accuracy, be correlated to voltage at the VccT contact. Valid over 3.3V ± 10%.
Transmitter Laser DC Bias Current Accuracy	I_{INT}	±15	%	I_{INT} accuracy is better than ±10% of the nominal value.
Transmitted Average Optical Output Power Accuracy	P_T	±5.0	dB	Average Power coupled into 50/125 µm multi-mode fiber. Valid from100 µW to 500 µW.
Received Average Optical Input Power Accuracy	P_R	±5.0	dB	Average Power coupled from 50/125 µm multi-mode fiber. Valid from 77 µW to 500 µW.

Figure 7: Transceiver Timing Diagrams (Module Installed and Power Applied Except Where Noted)
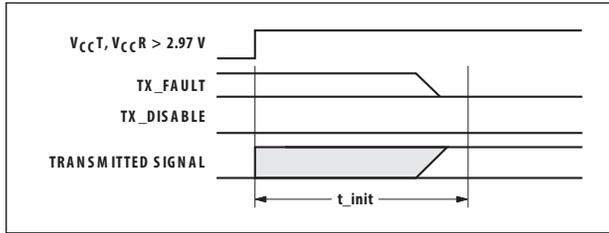
t-init: TX DISABLE NEGATED
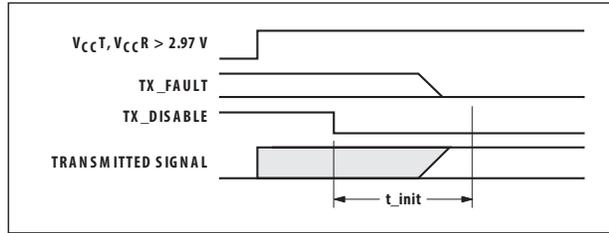
t-init: TX DISABLE ASSERTED
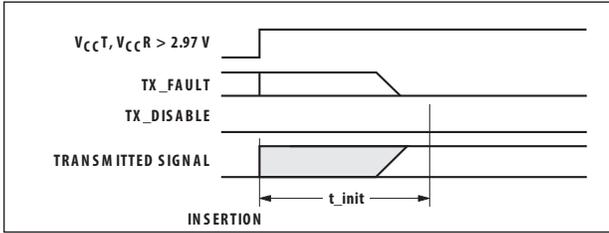
t-init: TX DISABLE NEGATED, MODULE HOT PLUGGED
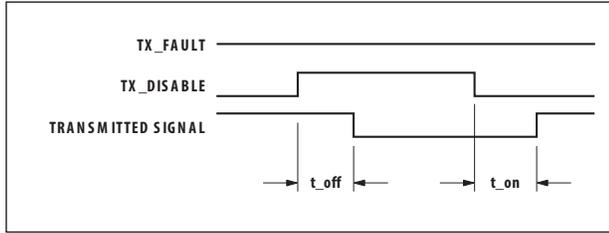
t-off & t-on: TX DISABLE ASSERTED THEN NEGATED
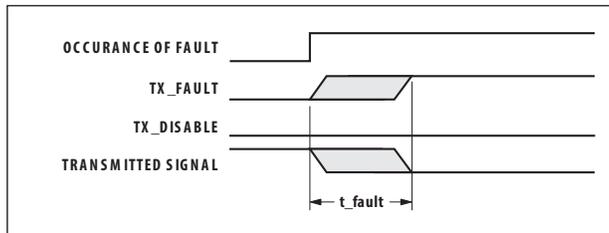
t-fault: TX FAULT ASSERTED, TX SIGNAL NOT RECOVERED
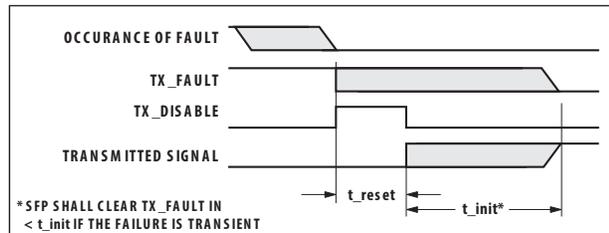
t-reset: TX DISABLE ASSERTED THEN NEGATED, TX SIGNAL RECOVERED
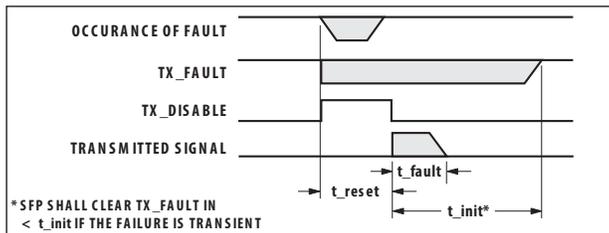
t-fault: TX DISABLE ASSERTED THEN NEGATED, TX SIGNAL NOT RECOVERED
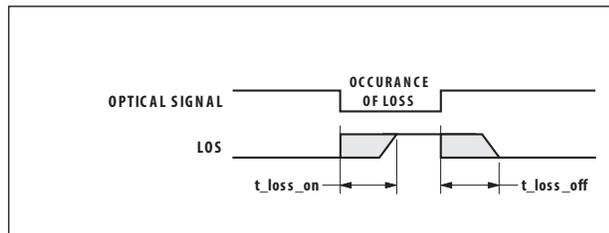
t-los-on & t-los-off

Table 12: EEPROM Serial ID Memory Contents – Conventional SFP Memory (Address A0h)

Byte Number Decimal	Data Hex	Notes	Byte Number Decimal	Data Hex	Notes
0	03	SFP physical device	37	00	Hex Byte of Vendor OUI[a]
1	04	SFP function defined by serial ID only	38	17	Hex Byte of Vendor OUI[a]
2	07	LC optical connector	39	6A	Hex Byte of Vendor OUI[a]
3	80		40	41	"A" – Vendor Part Number ASCII character
4	00		41	46	"F" – Vendor Part Number ASCII character
5	00		42	42	"B" – Vendor Part Number ASCII character

Table 12: EEPROM Serial ID Memory Contents – Conventional SFP Memory (Address A0h) (Continued)

Byte Number Decimal	Data Hex	Notes	Byte Number Decimal	Data Hex	Notes
6	00		43	52	"R" – Vendor Part Number ASCII character
7	00		44	2D	"-" – Vendor Part Number ASCII character
8	00		45	37	"7" – Vendor Part Number ASCII character
9	00		46	31	"1" – Vendor Part Number ASCII character
10	00		47	30	"0" – Vendor Part Number ASCII character
11	06	64B/66B	48	55	"U" – Vendor Part Number ASCII character
12	67	10312.5-Mb/s nominal bit rate (10.3125 Gb/s)	49	53	"S" – Vendor Part Number ASCII character
13	00	Unspecified	50	4D	"M" – Vendor Part Number ASCII character
14	00		51	5A	"Z" – Vendor Part Number ASCII character
15	00		52	20	" " – Vendor Part Number ASCII character
16	03	30m of OM2 50/125 μm fiber	53	20	" " – Vendor Part Number ASCII character
17	01	10m of OM1 62.5/125 μm fiber	54	20	" " – Vendor Part Number ASCII character
18	00		55	20	" " – Vendor Part Number ASCII character
19	0A	100m of OM3 50/125 μm fiber	56	20	" " – Vendor Revision Number ASCII character
20	41	"A" – Vendor Name ASCII character	57	20	" " – Vendor Revision Number ASCII character
21	56	"V" – Vendor Name ASCII character	58	20	" " – Vendor Revision Number ASCII character
22	41	"A" – Vendor Name ASCII character	59	20	" " – Vendor Revision Number ASCII character
23	47	"G" – Vendor Name ASCII character	60	03	Hex Byte of Laser Wavelength[b]
24	4F	"O" – Vendor Name ASCII character	61	52	Hex Byte of Laser Wavelength[b]
25	20	" " – Vendor Name ASCII character	62	00	
26	20	" " – Vendor Name ASCII character	63		Checksum for Bytes 0 to 62[c]
27	20	" " – Vendor Name ASCII character	64	00	Receiver limiting output. 1W power class.
28	20	" " – Vendor Name ASCII character	65	1A	Hardware SFP TX_DISABLE, TX_FAULT, and RX_LOS
29	20	" " – Vendor Name ASCII character	66	00	
30	20	" " – Vendor Name ASCII character	67	00	
31	20	" " – Vendor Name ASCII character	68–83		Vendor Serial Number ASCII characters[d]
32	20	" " – Vendor Name ASCII character	84–91		Vendor Date Code ASCII characters[e]
33	20	" " – Vendor Name ASCII character	92	68	Digital Diagnostics, Internal Cal, Rx Pwr Avg
34	20	" " – Vendor Name ASCII character	93	F0	A/W, Soft SFP TX_DISABLE, TX_FAULT, and RX_LOS
35	20	" " – Vendor Name ASCII character	94	03	SFF-8472 Compliance to revision 10.4
36	00		95		Checksum for Bytes 64 to 94[c]
			96–255	00	

a. The IEEE Organizationally Unique Identifier (OUI) assigned to Broadcom is 00-17-6A (3 bytes of hex).

b. Laser wavelength is represented in 16 unsigned bits. The hex representation of 850 (nm) is 0352.

c. Addresses 63 and 95 are checksums calculated (per SFF-8472) and stored prior to product shipment.

d. Addresses 68–83 specify the AFBR-710USMZ ASCII serial number and vary on a per-unit basis.

e. Addresses 84–91 specify the AFBR-710USMZ ASCII date code and vary on a per-date code basis.

Table 13: EEPROM Serial ID Memory Contents – Enhanced Feature Set Memory (Address A2h)

Byte Number Decimal	Notes	Byte Number Decimal	Notes	Byte Number Decimal	Notes
0	Temp H Alarm MSB[a]	26	Tx Pwr L Alarm MSB[g]	104	Real Time Rx Pwr MSB[b]
1	Temp H Alarm LSB[a]	27	Tx Pwr L Alarm LSB[g]	105	Real Time Rx Pwr LSB[b]
2	Temp L Alarm MSB[a]	28	Tx Pwr H Warning MSB[g]	106	Reserved
3	Temp L Alarm LSB[a]	29	Tx Pwr H Warning LSB[g]	107	Reserved
4	Temp H Warning MSB[a]	30	Tx Pwr L Warning MSB[g]	108	Reserved
5	Temp H Warning LSB[a]	31	Tx Pwr L Warning LSB[g]	109	Reserved
6	Temp L Warning MSB[a]	32	Rx Pwr H Alarm MSB[b]	110	Status/Control – See Table 14
7	Temp L Warning LSB[a]	33	Rx Pwr H Alarm LSB[b]	111	Reserved
8	Vcc H Alarm MSB[c]	34	Rx Pwr L Alarm MSB[b]	112	Flag Bits – See Table 15
9	Vcc H Alarm LSB[c]	35	Rx Pwr L Alarm LSB[b]	113	Flag Bits – See Table 15
10	Vcc L Alarm MSB[c]	36	Rx Pwr H Warning MSB[b]	114	Reserved
11	Vcc L Alarm LSB[c]	37	Rx Pwr H Warning LSB[b]	115	Reserved
12	Vcc H Warning MSB[c]	38	Rx Pwr L Warning MSB[b]	116	Flag Bits – See Table 15
13	Vcc H Warning LSB[c]	39	Rx Pwr L Warning LSB[b]	117	Flag Bits – See Table 15
14	Vcc L Warning MSB[c]	40–55	Reserved	118–127	Reserved
15	Vcc L Warning LSB[c]	56–94	External Calibration Constants[d]	128–247	Customer Writeable
16	Tx Bias H Alarm MSB[e]	95	Checksum for Bytes 0 to 94[f]	248–255	Vendor Specific
17	Tx Bias H Alarm LSB[e]	96	Real Time Temperature MSB[a]		
18	Tx Bias L Alarm MSB[e]	97	Real Time Temperature LSB[a]		
19	Tx Bias L Alarm LSB[e]	98	Real Time Vcc MSB[c]		
20	Tx Bias H Warning MSB[e]	99	Real Time Vcc LS[c]		
21	Tx Bias H Warning LSB[e]	100	Real Time Tx Bias MSB[e]		
22	Tx Bias L Warning MSB[e]	101	Real Time Tx Bias LSB[e]		
23	Tx Bias L Warning LSB[e]	102	Real Time Tx Power MSB[g]		
24	Tx Pwr H Alarm MSB[g]	103	Real Time Tx Power LSB[g]		
25	Tx Pwr H Alarm LSB[g]				

a. Temperature (Temp) is decoded as a 16-bit signed twos' complement integer in increments of 1/256°C.

b. Received average optical power (Rx Pwr) is decoded as a 16-bit unsigned integer in increments of 0.1 µW.

c. Supply Voltage (Vcc) is decoded as a 16-bit unsigned integer in increments of 100 µV.

d. Bytes 56–94 are not intended for use with AFBR-710USMZ, but have been set to default values per SFF- 8472.

e. Laser bias current (Tx Bias) is decoded as a 16-bit unsigned integer in increments of 2 µA.

f. Byte 95 is a checksum calculated (per SFF-8472) and stored prior to product shipment.

g. Transmitted average optical power (Tx Pwr) is decoded as a 16-bit unsigned integer in increments of 0.1 µW.

Table 14: EEPROM Serial ID Memory Contents – Soft Commands (Address A2h, Byte 110)

Bit Number	Status/ Control Name	Description	Notes
7	TX_ DISABLE State	Digital state of SFP TX_ DISABLE Input (1 = TX_DISABLE asserted)	a
6	Soft TX_ DISABLE	Read/write bit for changing digital state of TX_DISABLE function	a, b
5	Reserved		
4	Reserved		
3	Reserved		
2	TX_FAULT State	Digital state of the SFP TX_FAULT Output (1 = TX_FAULT asserted)	a
1	RX_LOS State	Digital state of the SFP RX_LOS Output (1 = RX_LOS asserted)	a
0	Data Ready (Bar)	Indicates transceiver is powered and real time sense data is ready. (0 = Ready)	

a. The response time for soft commands of the AFBR-708SMZ is 100 ms as specified by SFF-8472.

b. Bit 6 is logic ORed with the SFP TX_DISABLE input on contact 3; either asserted will disable the SFP+ transmitter.

Table 15: EEPROM Serial ID Memory Contents – Alarms and Warnings (Address A2h, Bytes 112, 113, 116, 117)

Byte	Bit	Flag Bit Name	Description
112	7	Temp High Alarm	Set when transceiver internal temperature exceeds high alarm threshold
	6	Temp Low Alarm	Set when transceiver internal temperature exceeds low alarm threshold
	5	Vcc High Alarm	Set when transceiver internal supply voltage exceeds high alarm threshold
	4	Vcc Low Alarm	Set when transceiver internal supply voltage exceeds low alarm threshold
	3	Tx Bias High Alarm	Set when transceiver laser bias current exceeds high alarm threshold
	2	Tx Bias Low Alarm	Set when transceiver laser bias current exceeds low alarm threshold
	1	Tx Power High Alarm	Set when transmitted average optical power exceeds high alarm threshold
	0	Tx Power Low Alarm	Set when transmitted average optical power exceeds low alarm threshold
113	7	Rx Power High Alarm	Set when received average optical power exceeds high alarm threshold
	6	Rx Power Low Alarm	Set when received average optical power exceeds low alarm threshold
	0–5	Reserved	
116	7	Temp High Warning	Set when transceiver internal temperature exceeds high warning threshold
	6	Temp Low Warning	Set when transceiver internal temperature exceeds low warning threshold
	5	Vcc High Warning	Set when transceiver internal supply voltage exceeds high warning threshold
	4	Vcc Low Warning	Set when transceiver internal supply voltage exceeds low warning threshold
	3	Tx Bias High Warning	Set when transceiver laser bias current exceeds high warning threshold
	2	Tx Bias Low Warning	Set when transceiver laser bias current exceeds low warning threshold
	1	Tx Power High Warning	Set when transmitted average optical power exceeds high warning threshold
	0	Tx Power Low Warning	Set when transmitted average optical power exceeds low warning threshold
117	7	Rx Power High Warning	Set when received average optical power exceeds high warning threshold
	6	Rx Power Low Warning	Set when received average optical power exceeds low warning threshold
	0–5	Reserved	

Figure 8: Module Drawing

BROADCOM®